

# Power Devices Business Briefing

Providing crucial energy-saving devices
 as a global top-level power devices manufacturer —

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### Contents

- 1. Introduction
- 2. Positioning and Features of Business
- 3. Business Environment
- 4. Growth Targets
- 5. Differentiation Strategy
- 6. Business Strategy by Segment
- 7. Manufacturing Strategy
- 8. Summary



#### 1. Introduction

#### **Embodiment of the Corporate Mission**

#### **Corporate Mission**

The Mitsubishi Electric Group will continually improve its technologies and services by applying creativity to all aspects of its business.

By doing so, we enhance the quality of life in our society.

#### [Contemporary Social Issues]

Environmental issues

Resource/ Energy issues

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#### [Initiatives of Mitsubishi Electric Group]

Global Development of Products, Systems, and Services

Make Strong Businesses Technology Synergies/

Stronger Businesses Business Synergies

Realize a Sustainable Society

Provide Safety, Security, and Comfort

#### [Embodiment of the Corporate Mission in the Context of the Current Environment]

Growth Targets to be Achieved by FY2020

Net Sales 5 trillion yen or more

OPM 8% or more

"Global, Leading Green Company"

Contribute to the realization

of a prosperous society



#### 1. Introduction

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Global Development of Products, Systems, and Services

Make Strong Businesses
Stronger

Technology Synergies/
Business Synergies

Realize a Sustainable Society

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#### [Embodiment of the Corporate Mission in the Context of the Current Environment]

Growth Targets to be Achieved by FY2022

Net Sales 200 billion yen OPM 10%

"Global, Leading Green Company"

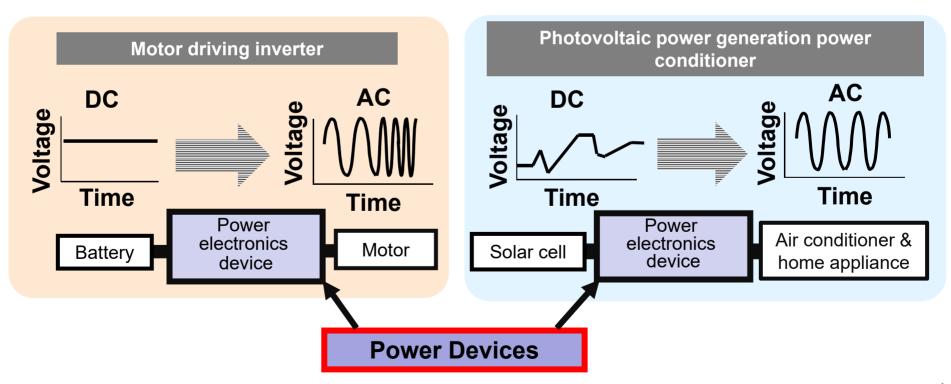
Contribute to the realization

of a prosperous society



#### Power devices are crucial for low-carbon societies

- ➤ Semiconductor devices that efficiently control electric power by converting electricity from DC to AC, DC to AC, or by raising or lowering voltage
- ➤ Key energy saving devices used in a wide range of sectors including power control for industrial machinery, traction, electric vehicles (EV\*), home appliances, photovoltaic power generation, wind power generation, motor control, and more.





#### Positioned as a business to drive corporate growth

#### **Energy & Electric Systems**

#### Power Systems-

Power generation systems, Transmission & distribution systems, Power distribution systems, Particle therapy systems, etc.

#### Transportation Systems

Inverters, main motors and air conditioning systems for railcars, Train Vision, Train control and management systems, Railcar operation management systems, Signaling systems, etc.

#### Building Systems-

Elevators, Escalators, Building management systems, etc.

Public Systems
 Water treatment systems,
 Disaster prevention systems, etc.

#### **Industrial Automation Systems**

 Factory Automation (FA) -Systems

PLCs, AC servomotors, CNCs, Industrial robots, Laser processing machines, etc.

Automotive Equipment-

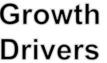
Starters, Alternators, Car multimedia, EPS system products, Electric powertrain system, etc.

















#### Information & Communication Systems

#### Space Systems

Satellites, Ground systems for satellite control, etc.

- Defense Systems
   Radar equipment, Antennas, etc.
- Communication Systems
   Optical, wireless and satellite communications systems, etc.
- Video Monitoring Systems
   Network camera systems
- IT Solution

#### **Electronic Devices**

- Power Devices
   SiC¹ modules, IGBT² modules, etc.
- High Frequency and Optical Devices
   High frequency devices (GaN³ and GaAs⁴), Optical devices, etc.
- TFT<sup>5</sup> LCD Modules

#### **Home Appliances**

Air-Conditioning &

#### **Refrigeration Systems**

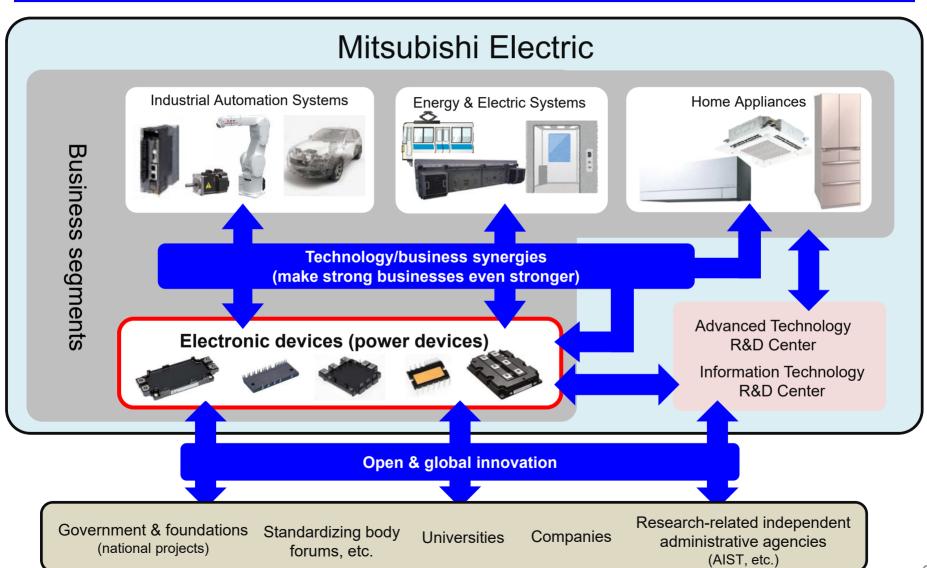
Room and package air conditioners, Multiple AC units for buildings, Lossnay ventilation systems, Chillers, etc.

- Housing Equipment Smart appliances, Lighting, HEMS, etc.
- Kitchen and Other Household
   Appliances
   Mitsubishi Electric Corporation

- 1 SiC: Silicon carbide 2 IGBT: Insulated gate bipolar transistor 3 GaN: Gallium nitride
- 4 GaAs: Gallium arsenide 5 TFT: Thin film transistor



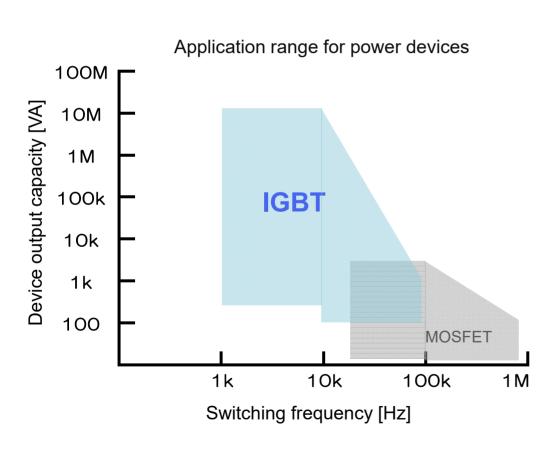
Strengths are in-house business and technology synergies, and global innovation

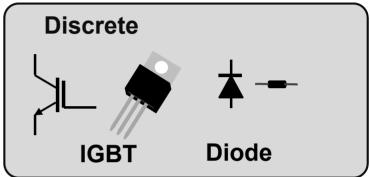


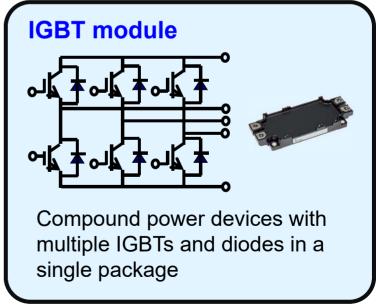


#### Our Focus: IGBTs and Modules

#### **IGBT** and **MOSFET**\*

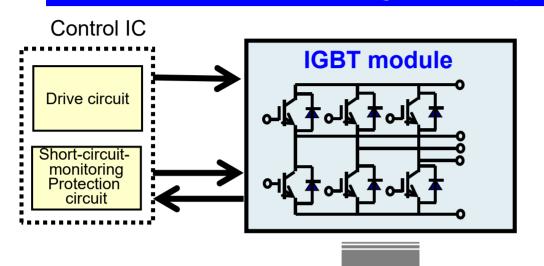




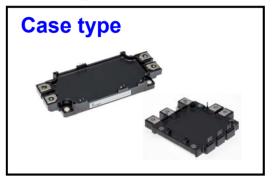


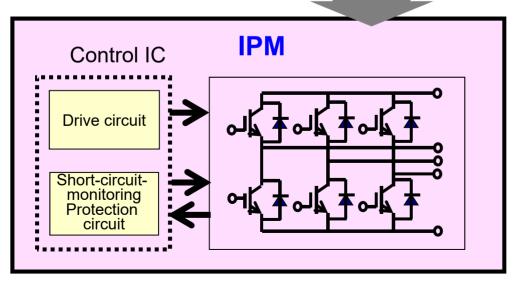


#### Focus on maintaining world's top share<sup>1</sup> in IPM<sup>2</sup>



#### **Package**



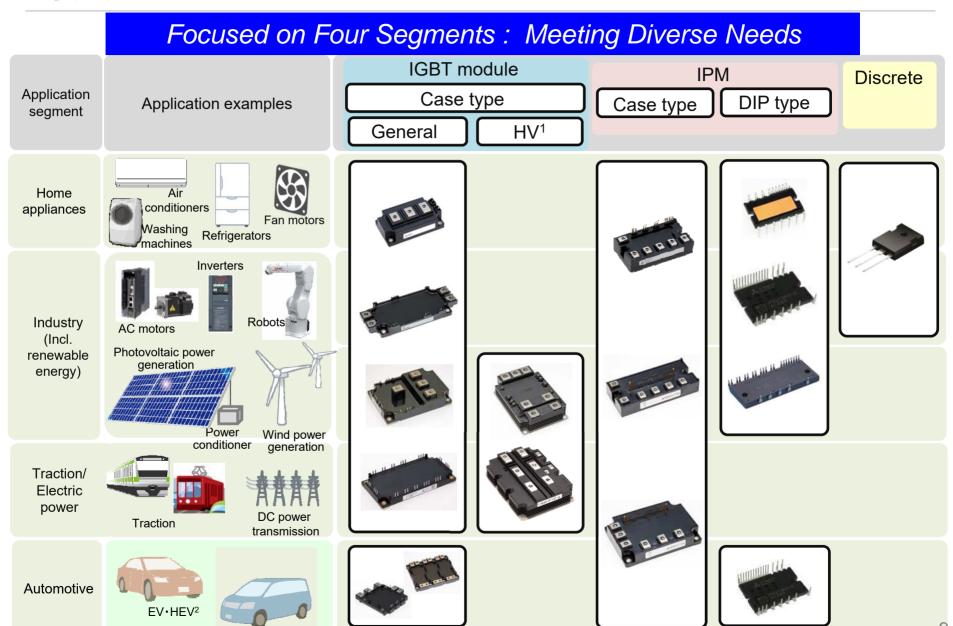


#### **Package**





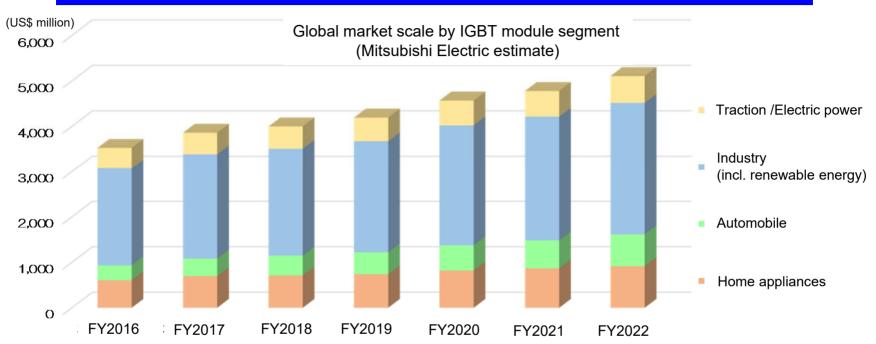






#### 3. Business Environment





#### Background of power devices market expansion

Home appliances: Growth due to expansion of market for major appliances (air conditioners, refrigerators, washing machines, etc.)

and progress in shift to inverters

Automotive: High growth due to accelerated shift to EVs due to more stringent environmental regulations

Expansion, mainly in FA market, due to investment in factory automation, power efficiency improvements, and Industry: (incl. renewable energy)

strengthened environmental regulations for motors (incl. renewable energy). Growth will accompany expansion of

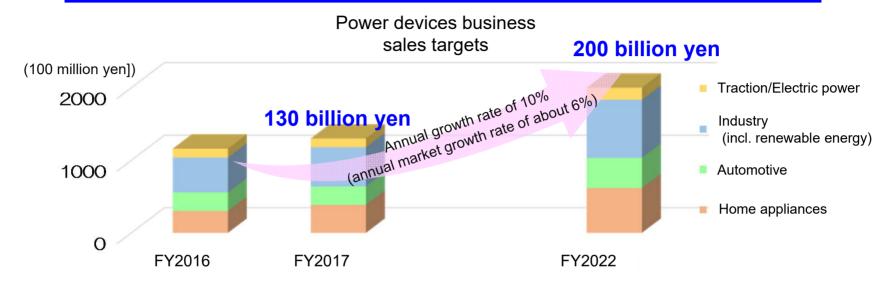
renewable energy (solar and wind) markets around the world.

Moderate growth in electric railway rolling stock market in line with population growth, urbanization, etc. Traction/Electric power:



# 4. Growth Targets

#### FY2022: Net sales of 200 billion yen and OPM of 10%



#### Growth strategy: 10% growth in focus segments (exceed market growth of 6%)

Home appliances: Enhance product lineup balanced with market demands (higher functionality, lower power loss,

and lower costs), aiming to become the undisputed market leader

Automotive: Capture opportunities in the shift to electric-power automobiles and grow strongly worldwide

Industry: Introduce competitive products to increase share in major markets for power device business

(incl. renewable energy)

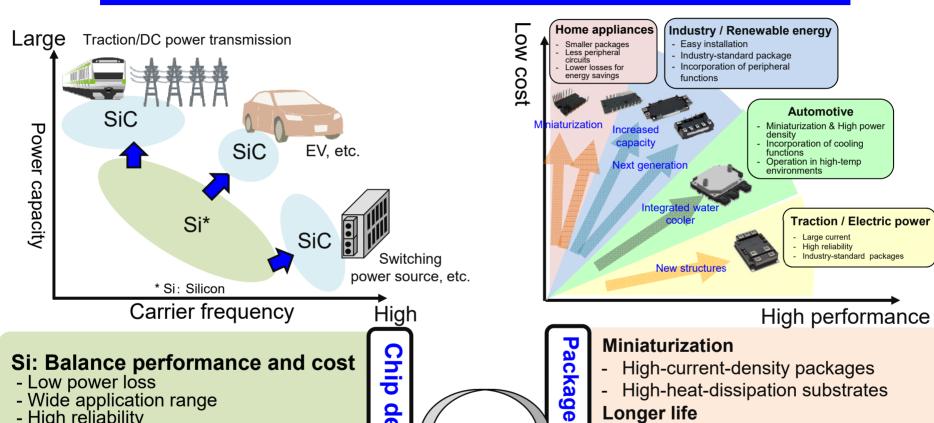
Traction/Electric power: Pursue greater added value in infrastructure segment where growth is not high but demands for

quality and reliability are high, to maintain the position as a top supplier



## 5. Differentiation Strategy

Developing high-efficiency power devices (chip)s and packages that match market needs are inseparable for differentiation



Chip

development

#### Si: Balance performance and cost

- Low power loss
- Wide application rangeHigh reliability

# SiC: High performance for valueadded applications - Lower power loss (70% less than Si) - High-frequency switching (100kHz class) - High temp. operation (200 °C class)

#### **Miniaturization**

- High-current-density packages
- High-heat-dissipation substrates

#### Longer life

development

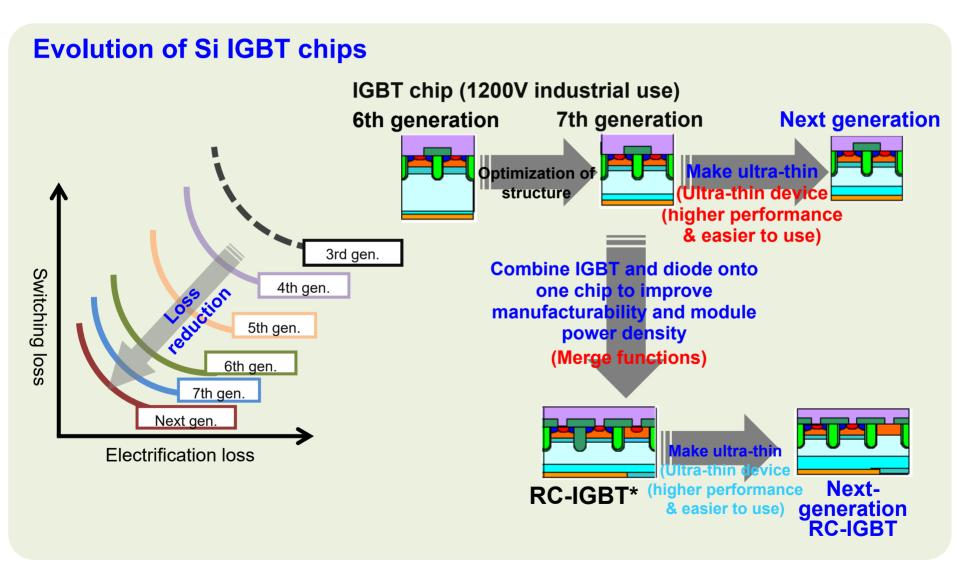
- Low-stress structure at heat cycle
- Low-thermal-resistance materials (bonding materials & encapsulants)

#### **Higher functionality**

- Integrated radiators
- Incorporation of peripheral circuits



# 5. Differentiation Strategy: Si IGBT chips

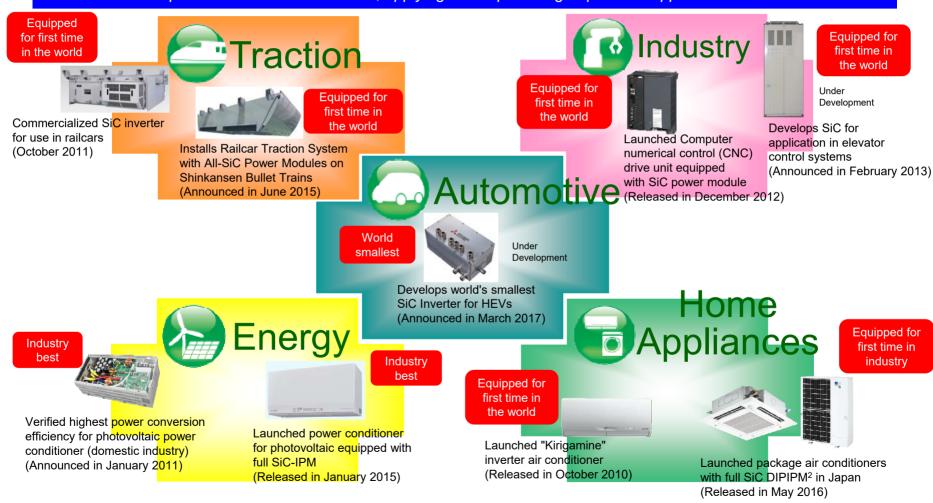




# 5. Differentiation Strategy: SiC

#### Become No.1 in many SiC applications<sup>1</sup>

- > Pursue advanced achievements through synergy among strong power electronics business units within company
- ➤ Introduce SiC power modules from the start, applying SiC to product groups for all applications



Development of these modules and applications has been partially supported by Japan's Ministry of Economy Trade and Industry (METI) and New Energy and Industrial Technology Development Organization (NEDO).

<sup>1</sup> The year and month listed are based on press releases or information released during the product launch month in Japan.

<sup>2</sup> DIPIPM: Registered trademark of Mitsubishi Electric Corporation



# 5. Differentiation Strategy: SiC chips

#### Continuous development of SiC to lower costs and improve performance

#### Features of SiC chips

Item	Si	SiC	Customer benefits	Combined uses
Power loss	1	1/3	High efficiency, higher output and energy savings	EVs, air conditioner, railways, and DC power transmission
High temp. operation	175°C	Tj>200°C	Reduced heat-dissipation fins	EVs and special inverters
High-speed switch	30KHz	Fc>100KHz	High efficiency and smaller size	Power sources and non-contact power supply

#### Advancement of SiC chips

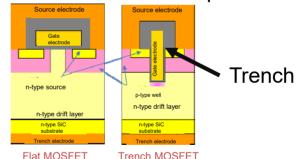
# ➤ Trench MOSFET ⇒Smaller size/Low loss/High reliability

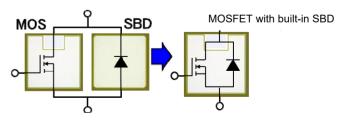
- Gate placed on wall of trench formed downward and cell density improved/refined with aim of lowest loss in the industry
- Original field alleviating structure employed to improve reliability

#### ➤ MOSFET with built-in SBD\* ⇒ Smaller size/Low cost

- Mitsubishi Electric original technology where chip is miniaturized by building SBD in to MOS Effective especially for high-voltage devices and has approx. 60% surface area for 3.3kV

#### MOSFET structure comparison





Chip surface area reduction by building in SBD (image)

Forward-looking R&D is pursuing new-material power devices, such as vertical GaN and gallium oxide, in addition to SiC-IGBT (current MOSFET)

\* SBD: Schottky barrier diode



# 6. Business Strategy by Segment: Home appliances

DIPIPM utilizing transfer mold technology

High-quality and diverse product lineup

Our strengths and features

Application technology and customer support capability for top share in segment

World's top production capacity and stable supply support capabilities

#### **Growth strategy**

Enhance product lineup balanced with market demands (higher functionality, lower power loss, and lower costs) with the goal of being the undisputed market leader

Capture more share where inverter use is expected to grow:
Washing machines

(2017: 19%<del>→</del>2022: 62%)

Refrigerators

 $(2017: 18\% \rightarrow 2022: 40\%)$ 

**→**Lower costs

- ➤ Enter small-capacity fan-motor market
  →Lower costs
- ➤ For existing RAC/PAC\*, gradually develop new markets in developing economies where switch to inverters is progressing (roughly double from 2017 to 2022) →Lower costs
- ➤ Introduce SiC products in luxury device market
   → Energy savings and higher

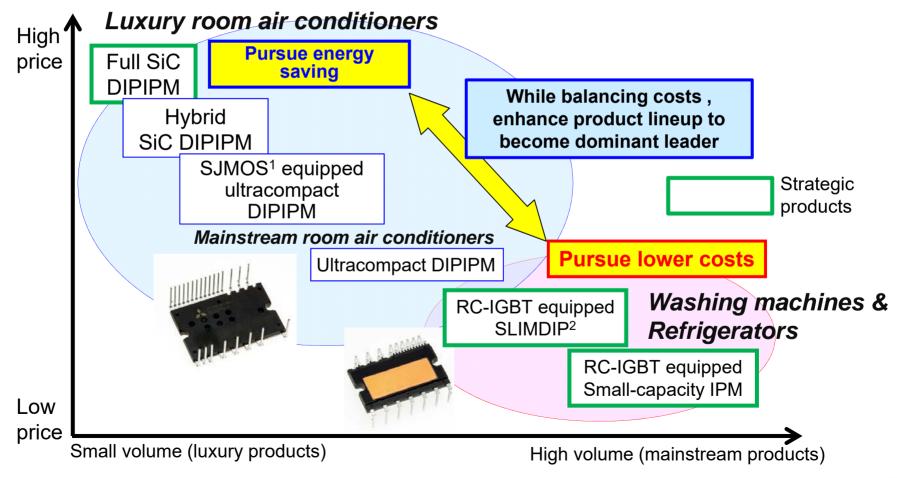
functionality



## 6. Business Strategy by Segment: Home appliances

#### Product strategy

- ➤ Higher functionality: More products equipped with SiC and reduce loss
- ➤ Lower costs: Apply RC-IGBT chips and low-cost packages





# 6. Business Strategy by Segment: Automotive

Ability to offer diverse solutions according to customer demands (chips & modules)

# Our strengths and features

High quality, strong technical application Support, and customersupport abilities

Abundant know-how and goodmarket performance from start of EV market



### Growth strategy

Capture opportunities in shift to electricpower automobiles and grow strongly worldwide

- ➤ Shift focus from Japan to overseas markets
- ➤ Shift development and delivery from customized to standardized products
- Deploy standardized modules (J/J1 series) globally
- ➤ Raise chip performance Si: Raise IGBT and RC-IGBT performance

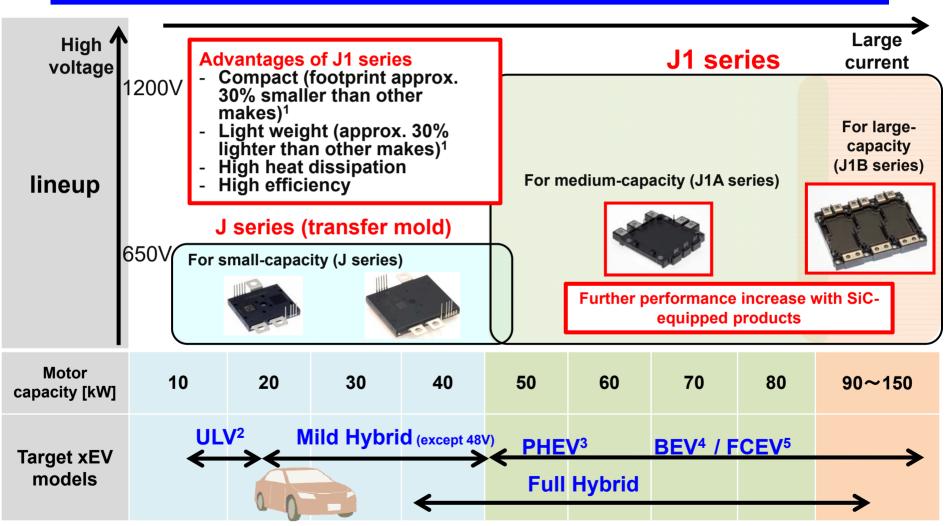
SiC: Shift to 6-inch and trench type



## 6. Business Strategy by Segment: Automotive

#### Standard module product strategy

> Expand product lineup according to market demands (high voltage, large current)





# 6. Business Strategy by Segment: Industry, incl. Renewable Energy

Know-how accumulated serving Japanese users over many decades and market performance

Our strengths and features

Products offering competitive advantages based on 7th generation chips and new package technologies

High quality, strong technical application support and customer support abilities

#### **Growth strategy**

Increase share in major markets for power devices business with competitive products

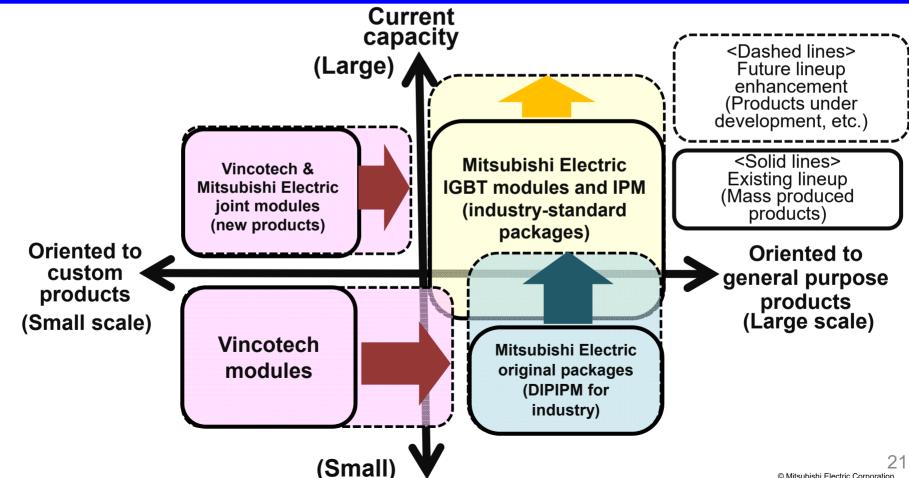
- ➤ Focus on business in European and Chinese markets while maintaining high market share in Japan
- > Focus on energy storage, charging, and EV buses as new markets
- Increased strategic original packages in addition to industrial-standard packages
- ➤ Increased intelligent products (for IoT\*)
- Develop products and synergies with Vincotech (German)



# 6. Business Strategy by Segment: Industry, incl. Renewable Energy

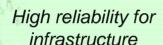
#### Product strategy

- ➤ Medium- and large-capacity products: Enhance industry-standard packages and increase capacities
- > Small-capacity products: Enhance lineup of DIPIPM original packages (No.1 among home appliances ) and pursue lower costs and higher quality
- > Transfer medium- and large-capacity technologies to Vincotech to capture custom products market





# 6. Business Strategy by Segment: Traction and Electric power



# Our strengths and features

Unmatched record and know-how in high-voltage segment

Top record\* in mass production of high-voltage SiC module products

#### **Growth strategy**

Pursue greater added value in infrastructure segment, where growth is not high but high quality/reliability are demanded, to maintain position as a top supplier

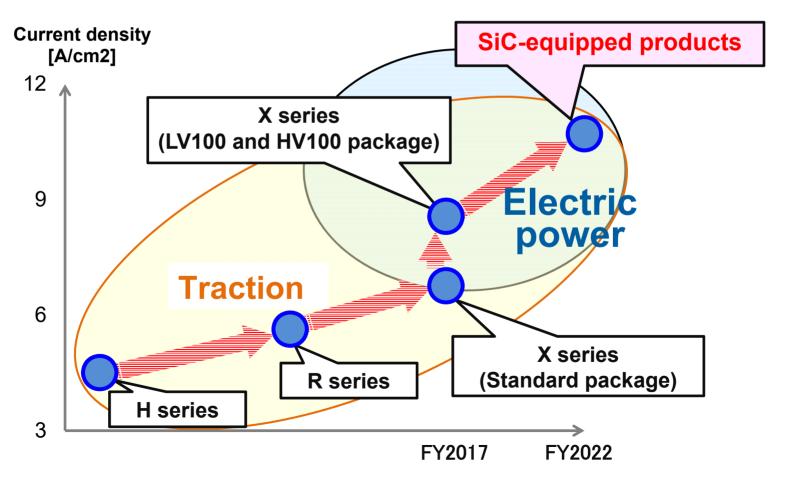
- ➤ Deploy products that utilize latest Si technologies (X series: equipped with first 7th generation 8-inch chips and employs latest packaging technology)
- Deploy high-voltage, low-loss SiC module products (3.3kV and 1.7kV)
- Continue to develop Chinese and Indian markets, where solid demand is expected for railways.
- ➤ Focus on DC power transmission, where future expansion is anticipated in Europe, North America and China



# 6. Business Strategy by Segment: Traction/Electric power

### **Product strategy**

Expand applications in traction and electric-power market by introducing products with current densities exceeding those of other makes





## 7. Production Strategy: Wafer Production

- ➤ Maintain highly added-value processes that are key to differentiation at company factories and continue to make investments (Si wafer back side processing and SiC wafers)
- ➤ Maximize production subcontracting (fabrication outsourcing) for Si wafer surface processing involving mainly general technologies and expand capacity while minimizing investments
- ➤ Utilize IoT and promote thorough productivity improvements
- ➤ Promote transition to multiple production lines to fortify BCP\*

# Surface processing Wafer Back side processing\*

\*Process specific to power wafers where electrodes, etc. are formed after grinding back side of wafer

# Kumamoto (Koshi City): Mother factory Wafer-surface and back-side processing (including SiC)



Fukuoka
(Fukuoka City):
SiC wafer (4-inch)
surface and backside processing

Japan production outsourcing Si-wafer surface processing

# Hyogo (Itami City) Si-wafer back-side processing



Overseas production outsourcing (to be decided)
Si-wafer surface processing



## 7. Production Strategy (assembly/inspection)

- ➤ Establish global system based on local production and consumption
- ➤ Utilize IoT for thorough productivity improvements
- > Transition to multiple production lines to fortify BCP
- ➤ Internalize inspection technologies as know-how and advance them

# Assembly/inspection processes

# Fukuoka (Fukuoka City/Itoshima City): Mother factory

Automotive/Traction/ Home appliances products





# China (Hefei City/Shanghai City\*) Home appliances products



\*Outsourcing in Shanghai

# Hyogo (Itami City/Toyooka City) Industrial products



#### Hungary (Vincotech) Industrial products





# 8. Summary

